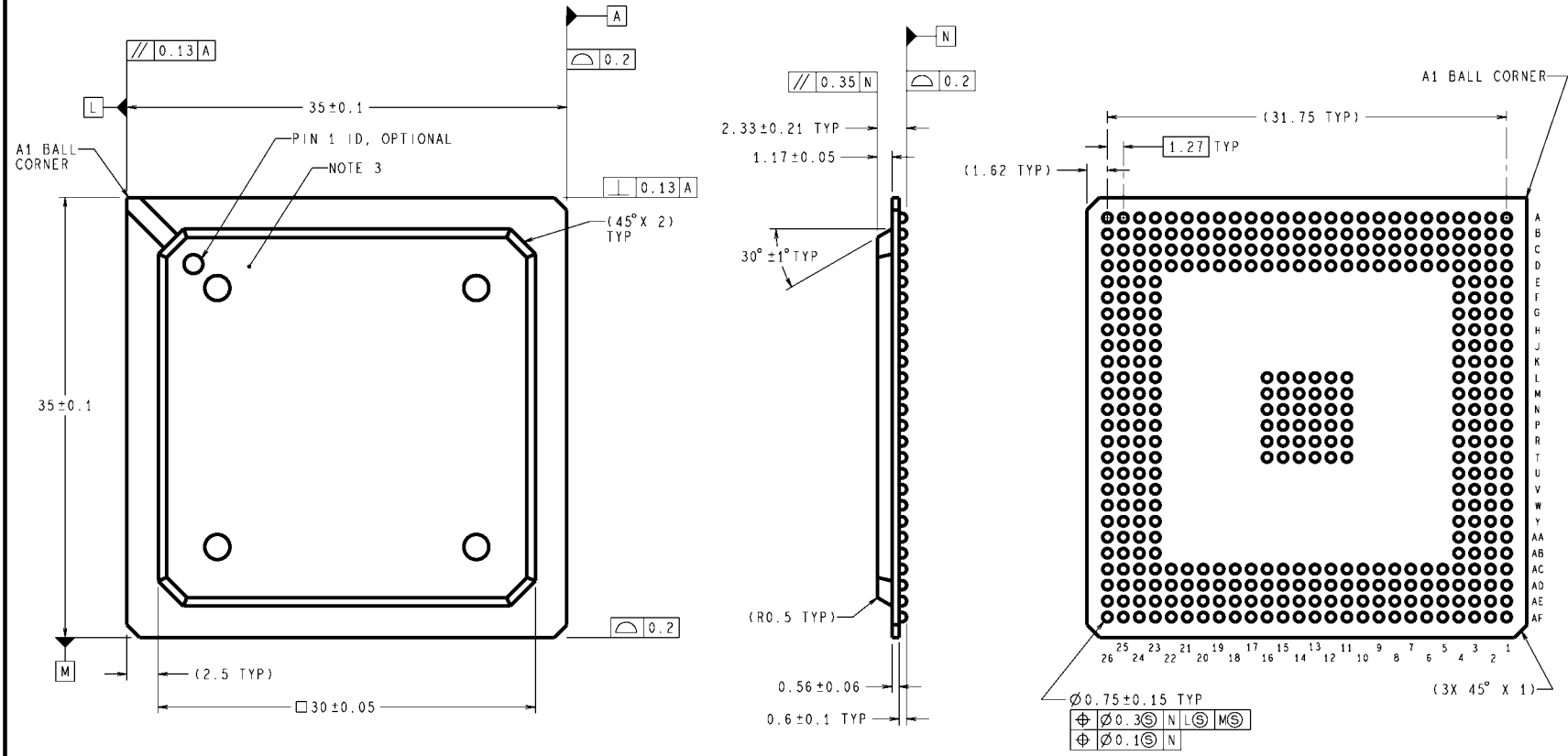


REVISIONS				
LTR	DESCRIPTION	E. C. N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11633	12/20/1999	fl/rb
B	Added RoHS ball composition; address change	9-0610-1	06/10/2009	fl/df



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. SOLDER BALL COMPOSITION: Sn 63%, Pb 37% non-RoHS; RoHS ball composition: 96.5%Sn, 3% Ag, 0.5% Cu
2. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
3. THE MOLD SURFACE AREA MAY INCLUDE DIMPLE FOR A1 BALL CORNER IDENTIFICATION.
4. REFERENCE JEDEC REGISTRATION MO-151, VARIATION -1.27 PITCH, DATED FEB. 1996.

APPROVALS		DATE	ZF Micro Solutions, Inc.		
DRWN	F. Lawrence	12/20/1999	926 Industrial Ave, Palo Alto, CA 94303-4300		
DTG. CHR.			PBGA, 35 X 35 X 2.33mm, 388 BALL, 1.27mm PITCH		
ENGR. CHR.					
		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(ISC)MKT-UCB388A	C
DO NOT SCALE DRAWING			SHEET 1 of 1		